Pittsburgh, PA 15217

OBJECTIVE

To apply my research engineering expertise hands-on to create industry-leading technologies

DDOFFCCIONAL EVDEDIENCE		
PROFESSIONAL EX 2012 – present	Assistant Research Professor of Electrical and Computer Engineering Carnegie Mellon University, Pittsburgh, PA • Driving multidisciplinary research for the biointegration of technology • Developing implantable neural probes and wearable biosensing devices • Directing a team of 8 research assistants and managing a microfabrication laboratory • Teaching electromechanics, semiconductor device physics and circuit analysis	
2010 – 2012	Post-Doctoral Research Fellow in Complex Engineered Systems Carnegie Mellon University, Pittsburgh, PA • Designed and fabricated ultra-compliant neural prostheses for chronic applications • Developed and deployed a web-based micro and nano-system design community	
2004 – 2010	Research Assistant in Electrical and Computer Engineering Carnegie Mellon University, Pittsburgh, PA • Designed and fabricated electrothermally actuated SOI-CMOS-MEMS micromirrors • Modeled plasma-etch-induced microstructure heating validated by infrared imaging • Modeled aspect ratio dependent etch and loading variation for DRIE Si etching	
2003 – 2004	Principal Process Engineer Bridge Semiconductor, Pittsburgh, PA • Developed thin-film co-polymer pyroelectric sensor integration on foundry CMOS • Developed backend process flow for pyroelectric infrared sensor fabrication • Produced integrated process flow documentation • Performed FMEA to identify critical processes and implemented SPC control for them	
1999 – 2003	Process Engineering Manager Infineon Technologies, Richmond, VA • Led a 24 person process engineering team in a high-volume DRAM process facility • Created a team that implemented Advanced Process Control (APC) for DRAM	
1996 – 1999	Process Engineer Siemens Microelectronics, Richmond, VA, Newcastle, UK and Dresden, Germany • Started-up 200 mm DRAM fabrication facilities in US and overseas • Qualified installed equipment for plasma etch fabrication processes • Implemented SPC procedures and produced documentation for etch processes	
1994 - 1996 1989 - 1991	Process Engineer GEC-Plessey Semiconductors Ltd., Swindon, England • Engineered bipolar semiconductor processes for all fabrication operations • Provided front line first response to fabrication yield and process control excursions	
1991 - 1993	Physics Teacher/Lab Manager Ghana Education Service, Accra, Ghana • Lectured on theoretical and practical physics to advanced placement level • Conducted physics labs and managed school physics lab	

EDUCATION	
May 2010	PhD in Electrical Engineering, Carnegie Mellon University, Pittsburgh, PA • Dissertation: SOI-CMOS-MEMS Electrothermal Micromirror Arrays
Jun. 2006	MSc in Electrical Engineering, Carnegie Mellon University, Pittsburgh, PA
Jun. 1989	BSc in Physics (1st Class Honours), Paisley College of Technology, Scotland

PROFESSIONAL SKILLS		
Engineering Design and Analysis Scripting	COMSOL Multiphysics, Coventor SEMulator, MATLAB-Simulink, Solidworks, JMP/Cornerstone, Cadence, Verilog-AMS Modeling, ImageJ MATLAB, Python, PERL, Mathematica, Verilog	
Microfabrication	2 Photon Lithography, 3-D Printing, Ion Milling, Mask Making, Plasma Etching, Acid Processing, Sputtering, Flip-chip Bonding, Dicing, Wirebonding, Spin-casting, Molding, Polishing/Grinding	
Analytics and Diagnostics	Scanning Electron Microscopy, White Light Interferometry, Profilometry, Infrared Imaging, Ellipsometry, Probe Station, Focused Ion Beam Imaging, Electrical Impedance Spectroscopy, Cyclic Voltammetry	
Advanced Process Control (APC)	Fault Detection and Classification (FDC), Run-to-Run (R2R)	
Failure Modes and Effects Analysis	Ford Model	
Statistical Process Control	6-sigma, Process Capability (Cp and Cpk), Stability (ISTAB)	
Design of Experiments	Full and Fractional Factorial Models, Taguchi	

PATENTS	
20140213891	Apparatus and Method for Implantation of Devices into Soft Tissue Assignee: Carnegie Mellon University
20130131482	Fabrication, Methods, Apparatuses, and Systems for Ultra-Compliant Probes for Neural and Other Tissues Assignee: Carnegie Mellon University
6,957,581	Acoustic Detection of Mechanically Induced Circuit Damage Assignee: Infineon Technologies Richmond, LP

PROFESSIONAL ACTIVITIES AND HONORS		
Senior Member	IEEE and Engineering in Medicine and Biology Society	
Technical Reviewer	IEEE Journal of Microelectromechanical Systems, Institute of Physics Journal of Micromechanics and Microengineering, American Institute of Physics Journal of Applied Physics	
Honor Society	Phi Kappa Phi, Carnegie Mellon University	